

Docket No. 618902001410  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Chun H. FAN et al.

Application No. 10/681,983

Confirmation No. 8846

Filed: October 9, 2003

Art Unit: 2826

For: MULTIPLE LEADFRAME LAMINATED IC  
PACKAGE

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Examiner: Leonardo Andujar

**AMENDMENT UNDER 37 CFR 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated June 15, 2007, please amend this application as follows.

**Amendments to the Specification** begin on page 2.

**Amendments to the claims** begin on page 3.

**Remarks** begin on page 5.